PCN Number:		20230322002.1					Date:	March 23, 2023	
Title:	Title: Qualification of a new die attach for select devices								
Custom	er Conta	ct: PCN	Manager	Dept:	Quality Services				
Proposed 1 <sup>st</sup> Ship Date: Jun 21			Jun 21	2023 Sample r		reques ed unt			
*Sampl	e reques	ts receiv	ed after	April 23, 3	2023 will not be s				
Change									
	embly Site			Design			afer Bum		
	embly Pro			Data S		Wafer Bump Material			
	embly Ma			Part number change			Wafer Bump Process		
		pecificatio ping/Labe		Test Site			Wafer Fab Site Wafer Fab Materials		
	king/Ship	pility/Labe	iiig	□ Test Process			Wafer Fab Materials		
				PCN	Details			100003	
Descrip	tion of C	hange:			Detailo				
<b>Description of Change:</b> This PCN is to inform of an alternate die attach qualification for the devices in the product affected section as follows:									
	v	Vhat			Current		New		
	Mount (	Compoun	d	4073502			4226802		
Reason	for Char	nge:							
Continui	ty of supp	bly							
Anticipa	ated imp	act on Fo	rm, Fit,	Function,	Quality or Reliabi	lity (po	sitive /	negative):	
None									
Impact	on Envir	onmenta	l Ratings	5					
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.									
RoHS			REACH		Green Stat	us	-	62474	
🛛 No Change			🛛 No Change		🛛 No Change		🛛 No Ch	ange	
Change	s to prod	luct iden	ification	reculting	from this PCN:				
None	3 to prod		incation	resulting	from this ren.				
	Affecte	d٠							
-		1	2006704	11.0/0			000774111		
	522101VXC		5962P8670411VYC		ADC08D1520WGMPR		MPD23774HKSH/EM		
	720401VXC		5962P8768105VYC		ADS1278HFQ/EM		MPD23797HKR		
	720402VXC		5962R0720802VXC		ADS1278MHFQ-MLS		TLK2711HFG/EM		
	-0720701VXC 5962R10221					TMP461HKU/EM TPS50301SHKH			
	0720801VXC 5962R102210								
	723001VXC		5962R1222403V		ADS5444HFG/EM		TPS50601AHKH/EM		
	924001VXC		52R13202		ADS5463HFG/EM				
5962-1(	)22101VSC	5962R1320202VXC		ADS5474HFG/EM		TPS7A4501HKU/EM			

5962-1022102VSC	5962R1320801VXC	ADS5474MHFGV	TPS7H1101AHKR/EM	
5962-1320201VXC	5962R1422801VXC	CDCM7005HFG/EM	TPS7H1101HKR/EM	
5962-1422801VXC	5962R1721801VXC	DAC5675AHFG/EM	TPS7H2201HKR/EM	
5962-1721801VXC	5962R1722001VXC	MPD23730HFG	TPS7H3301HKR/EM	
5962-1722001VXC	5962R8670412VYC	MPD23774HKH	UC1825BHKT/EM	
5962-9453001VXC	5962R8768106VYC	MPD23774HKSH	UC1843BHKU/EM	
5962P8670409VYC	ADC08D1520WGFQV			



TI Information Selective Disclosure

## Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Test Name / Condition	Condition	Qual Device: 5962-1820501VXC	Qual Device: 5962R1222403VXC
QML D3 Package Subgroup Sequence	a. TM 1011 Test condition B, 15 cycles minimum b. TM 1010 Test condition C, 100 cycles minimum c. TM 1004 d. In accordance with visual criteria of TM 1004 or TM 1010 e. TM 1014 test condition as applicable f. As specified in the applicable device	1/15/0	1/15/0
QML D4 Package Subgroup Sequence	a. TM 2002 condition B minimum b. TM 2007 condition A minimum c. TM 2001 Test condition E, Y1 orientation only d. TM 1014 condition as applicable e. In accordance with visual criteria of TM 2007 f. As specified in the applicable device specification Mech Shock + Vibration + Const Acceleration	1/15/0	1/15/0
QML D6 Package Subgroup Sequence	TM 1018 3(0) 5,000 ppm maximum water content at 100°C	1/3/0	1/3/0
Temperature Cycle	-65/150C, 500cycles	1/77/0	1/77/0
Electrical Characterization	Across Operating Temperature Range	1/30/0	1/30/0

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

REX ID: R-CHG-2204-003

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail		
WW Change Management Team	PCN ww admin team@list.ti.com		

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